

HD74HC85

4-bit Magnitude Comparator

REJ03D0555-0200
(Previous ADE-205-427)
Rev.2.00
Oct 06, 2005

Description

The HD74HC85 is designed for high speed comparison of two four bit words. This circuit has eight comparison input, 4 for each word; three cascade inputs ($A < B$, $A > B$, $A = B$); and three decision outputs ($A < B$, $A > B$, $A = B$). The result of a comparison is indicated by a high level on one of the decision outputs. Thus it may be determined whether one word is "greater than," "less than," or "equal to" the other word. By connecting the outputs of the least significant stage to the cascade inputs of the next stage, words of greater than four bits can be compared. In addition the least significant stage must have a high level applied to the $A = B$ input, and a low level to the $A < B$, and $A > B$ inputs.

Features

- High Speed Operation: t_{pd} (Data Word Input to Output) = 20 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC85P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—
HD74HC85FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)
HD74HC85RPEL	SOP-16 pin (JEDEC)	PRSP0016DG-A (FP-16DNV)	RP	EL (2,500 pcs/reel)

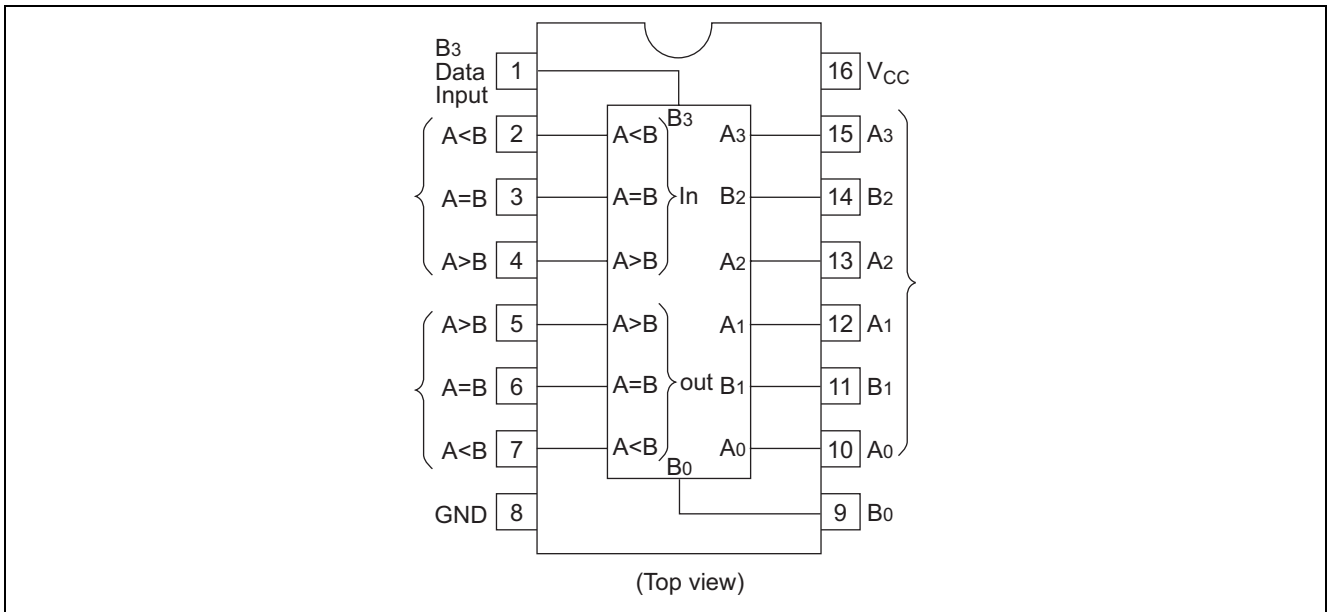
Note: Please consult the sales office for the above package availability.

Function Table

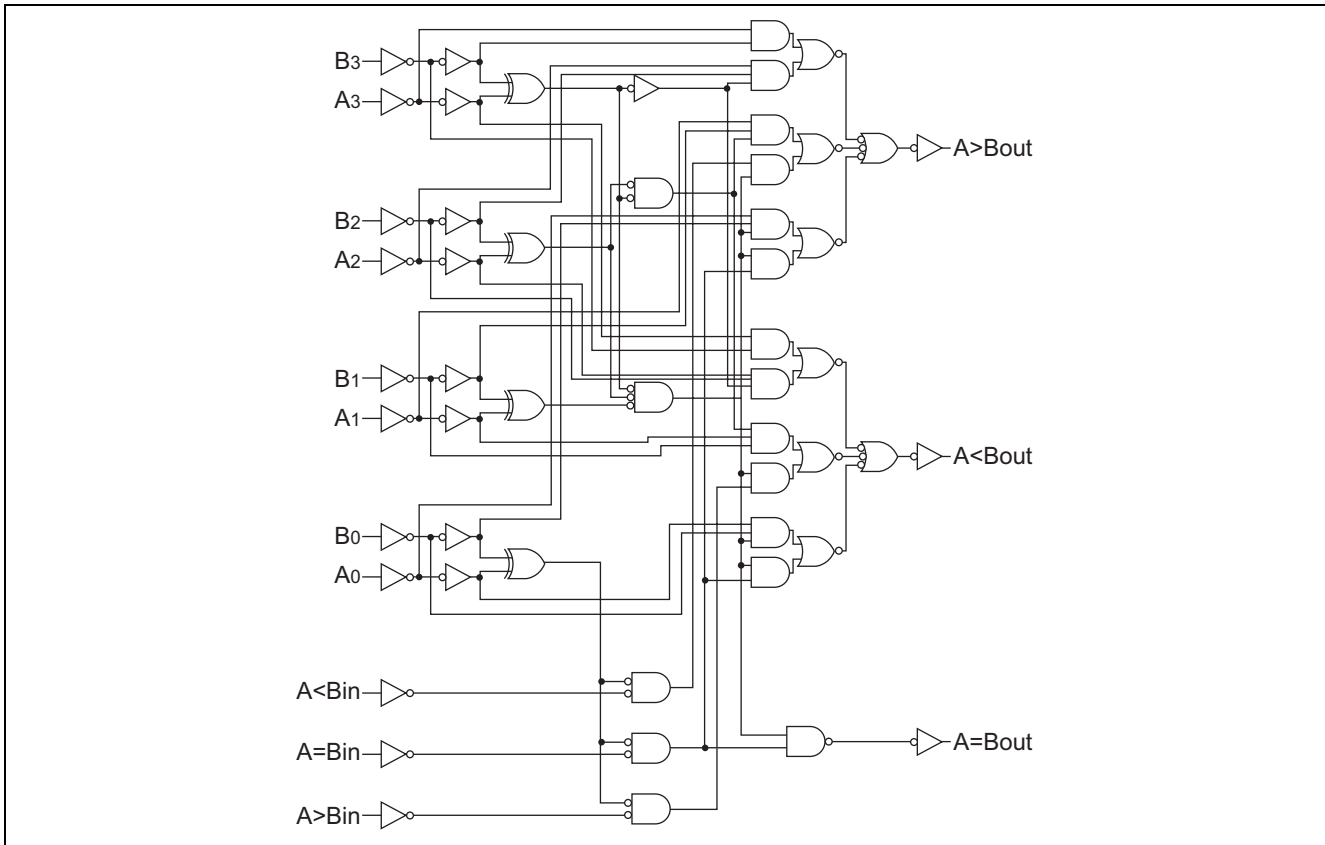
Data Word Inputs				Cascading Inputs			Outputs		
A ₃ , B ₃	A ₂ , B ₂	A ₁ , B ₁	A ₀ , B ₀	A > Bin	A = Bin	A < Bin	A > Bout	A = Bout	A < Bout
A ₃ > B ₃	X	X	X	X	X	X	H	L	L
A ₃ < B ₃	X	X	X	X	X	X	L	L	H
A ₃ = B ₃	A ₂ > B ₂	X	X	X	X	X	H	L	L
A ₃ = B ₃	A ₂ < B ₂	X	X	X	X	X	L	L	H
A ₃ = B ₃	A ₂ = B ₂	A ₁ > B ₁	X	X	X	X	H	L	L
A ₃ = B ₃	A ₂ = B ₂	A ₁ < B ₁	X	X	X	X	L	L	H
A ₃ = B ₃	A ₂ = B ₂	A ₁ = B ₁	A ₀ > B ₀	X	X	X	H	L	L
A ₃ = B ₃	A ₂ = B ₂	A ₁ = B ₁	A ₀ < B ₀	X	X	X	L	L	H
A ₃ = B ₃	A ₂ = B ₂	A ₁ = B ₁	A ₀ = B ₀	L	L	L	H	L	H
A ₃ = B ₃	A ₂ = B ₂	A ₁ = B ₁	A ₀ = B ₀	L	L	H	L	L	H
A ₃ = B ₃	A ₂ = B ₂	A ₁ = B ₁	A ₀ = B ₀	H	L	L	H	L	L
A ₃ = B ₃	A ₂ = B ₂	A ₁ = B ₁	A ₀ = B ₀	H	L	H	L	L	L
A ₃ = B ₃	A ₂ = B ₂	A ₁ = B ₁	A ₀ = B ₀	X	H	X	L	H	L

H : High level
 L : Low level
 X : Irrelevant

Pin Arrangement



Logic Diagram



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V_{CC}	-0.5 to 7.0	V
Input / Output voltage	V_{in}, V_{out}	-0.5 to $V_{CC} + 0.5$	V
Input / Output diode current	I_{IK}, I_{OK}	± 20	mA
Output current	I_O	± 25	mA
V_{CC}, GND current	I_{CC} or I_{GND}	± 50	mA
Power dissipation	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	$^{\circ}C$

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	2 to 6	V	
Input / Output voltage	V_{IN}, V_{OUT}	0 to V_{CC}	V	
Operating temperature	T_a	-40 to 85	$^{\circ}C$	
Input rise / fall time ^{*1}	t_r, t_f	0 to 1000	ns	$V_{CC} = 2.0 V$
		0 to 500		$V_{CC} = 4.5 V$
		0 to 400		$V_{CC} = 6.0 V$

Note: 1. This item guarantees maximum limit when one input switches.
Waveform: Refer to test circuit of switching characteristics.

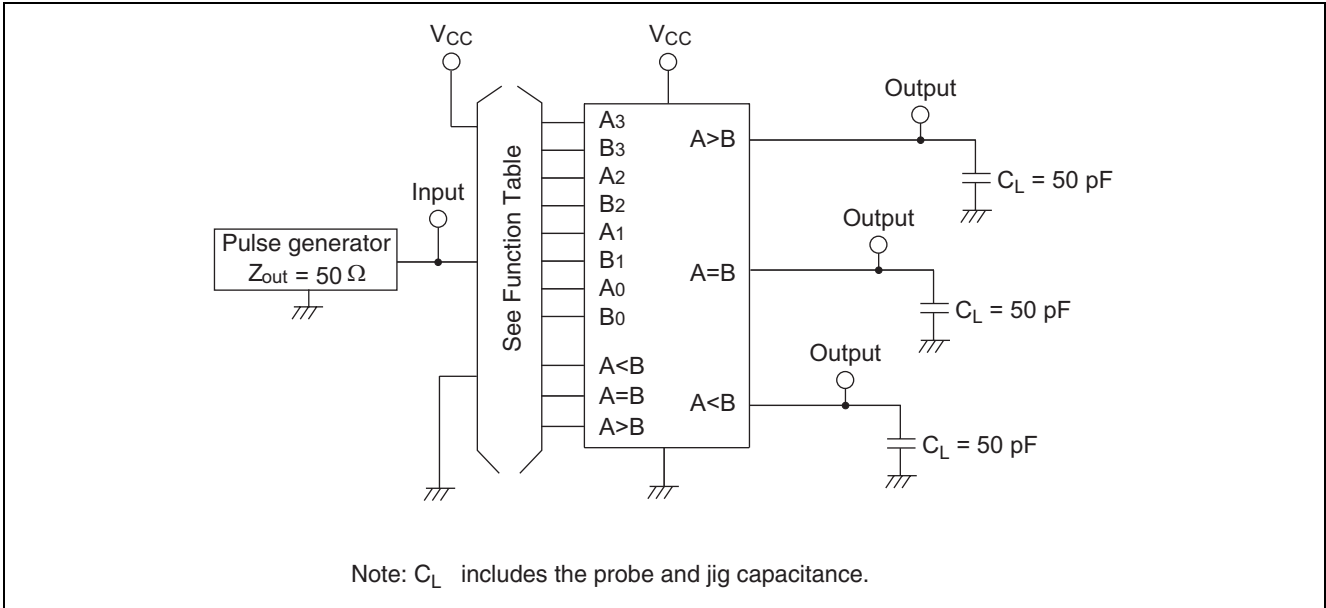
Electrical Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	V _{in} = V _{IH} or V _{IL}	I _{OH} = -20 μA
		4.5	4.4	4.5	—	4.4	—			I _{OH} = -4 mA
		6.0	5.9	6.0	—	5.9	—			I _{OH} = -5.2 mA
		4.5	4.18	—	—	4.13	—			
		6.0	5.68	—	—	5.63	—			
		6.0	5.68	—	—	5.63	—			
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	V _{in} = V _{IH} or V _{IL}	I _{OL} = 20 μA
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
		6.0	—	—	0.26	—	0.33			
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	V _{in} = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	V _{in} = V _{CC} or GND, I _{out} = 0 μA	

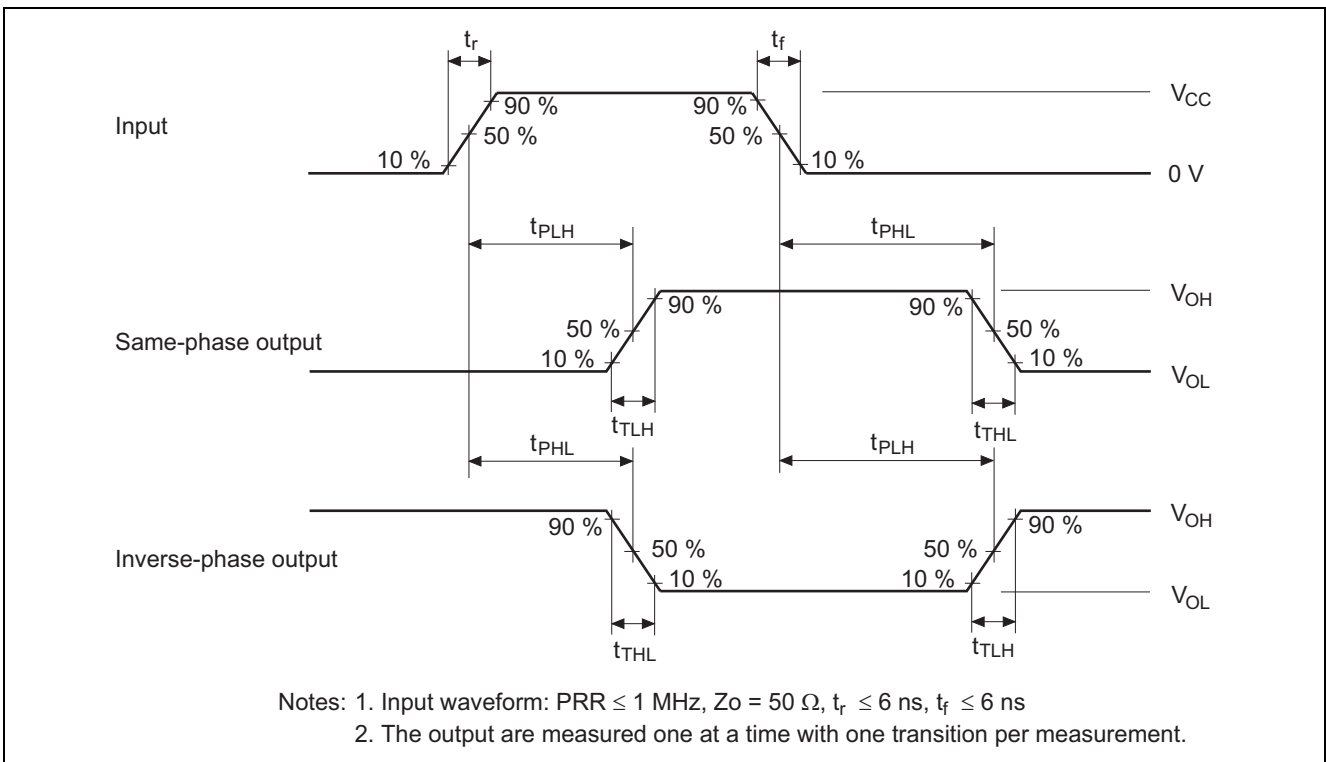
Switching Characteristics (C_L = 50 pF, Input t_r = t_f = 6 ns)

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Propagation delay time	t _{PLH} , t _{PHL}	2.0	—	—	210	—	265	ns	C ₀ to Σ ₁	
		4.5	—	20	42	—	53			
		6.0	—	—	36	—	45			
	t _{PLH} , t _{PHL}	2.0	—	—	175	—	220	ns	A ₁ or B ₁ to Σ ₁	
		4.5	—	20	35	—	44			
		6.0	—	—	30	—	37			
	t _{PLH} , t _{PHL}	2.0	—	—	125	—	155	ns	C ₀ to C ₄	
		4.5	—	12	25	—	31			
		6.0	—	—	21	—	26			
	t _{PLH} , t _{PHL}	2.0	—	—	155	—	195	ns	A ₁ or B ₁ to C ₄	
		4.5	—	14	31	—	39			
		6.0	—	—	26	—	33			
Output fall time	t _{THL}	2.0	—	—	75	—	95	ns		
		4.5	—	5	15	—	19			
		6.0	—	—	13	—	16			
Input capacitance	C _{in}	—	—	5	10	—	10	pF		

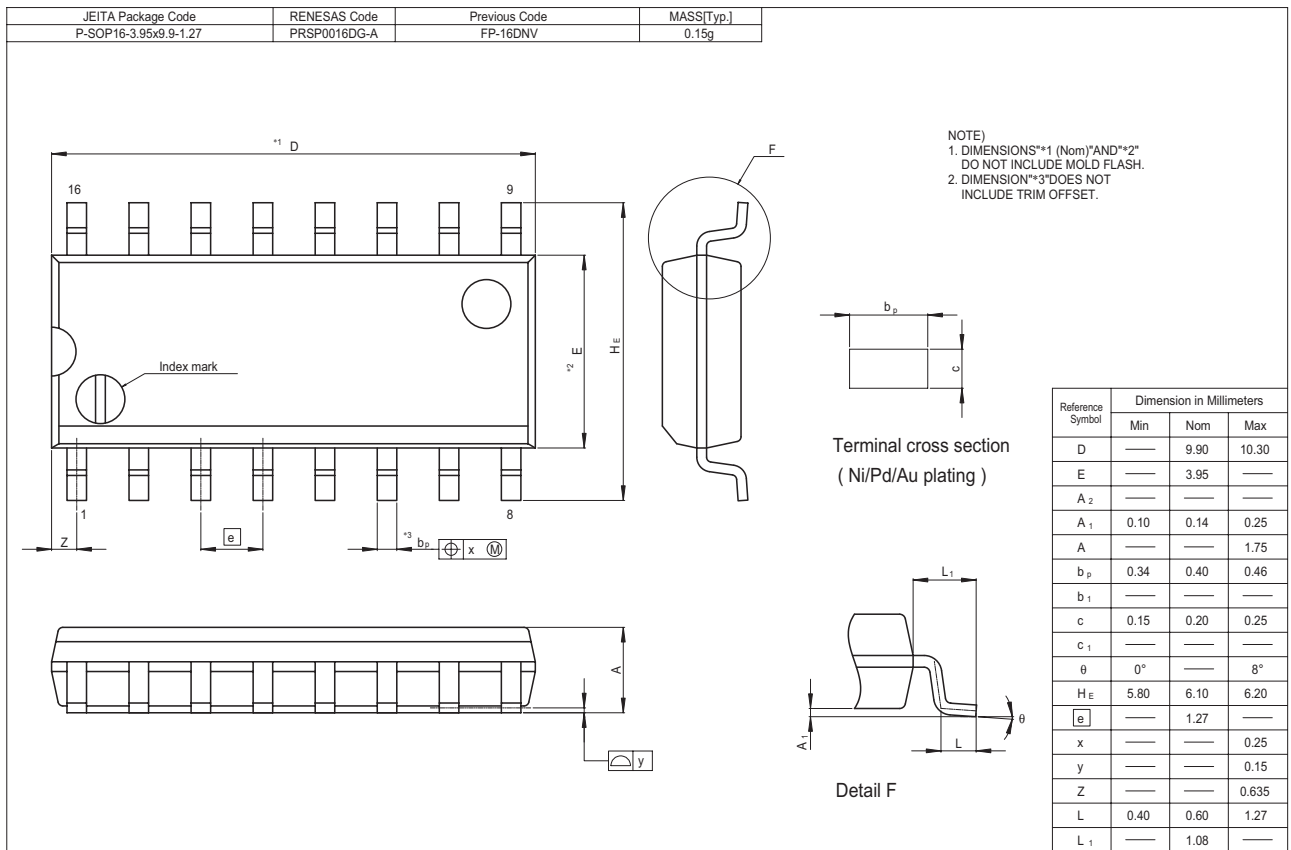
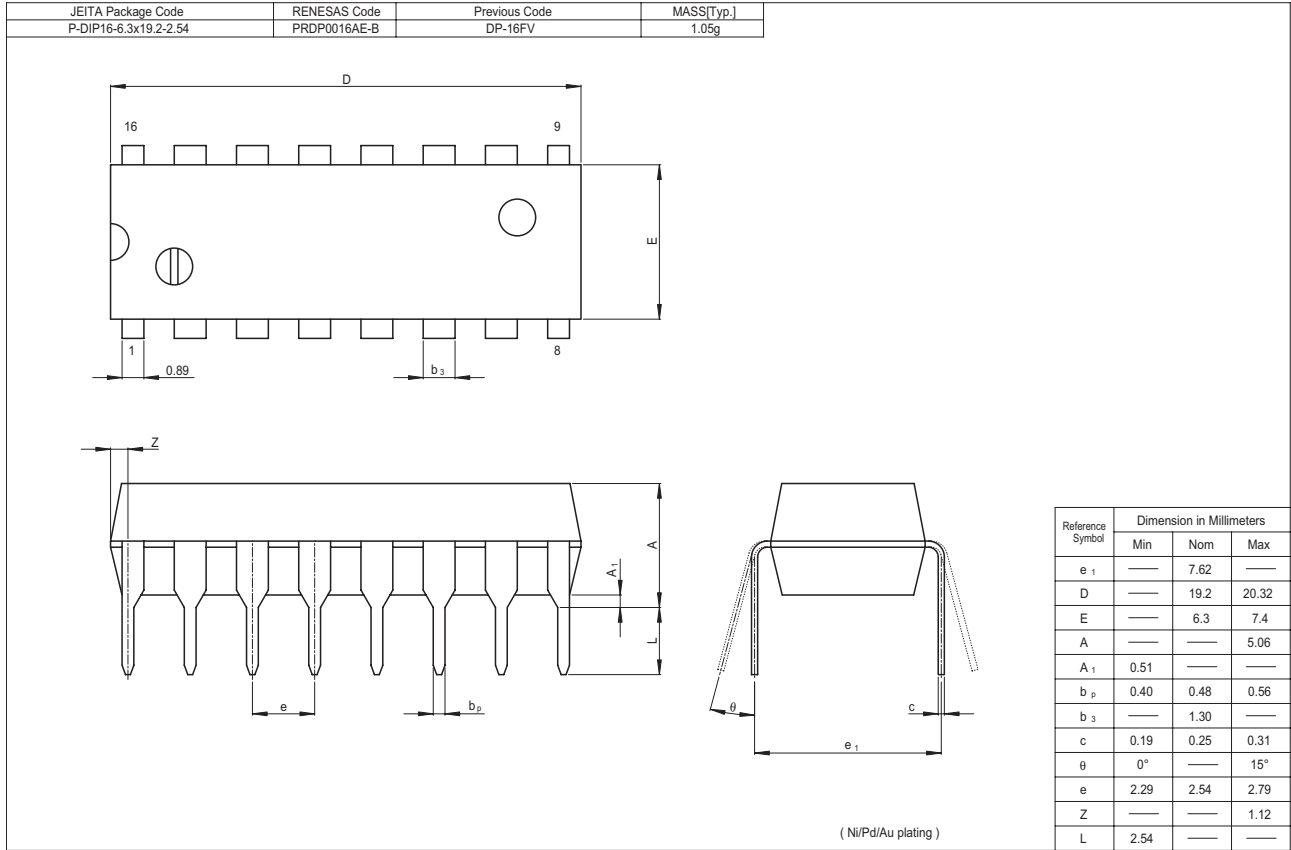
Test Circuit



Waveforms

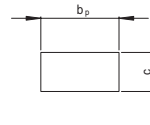
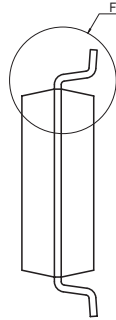
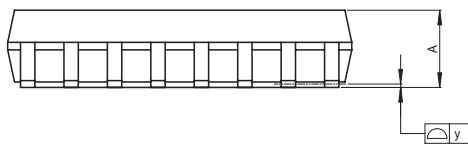
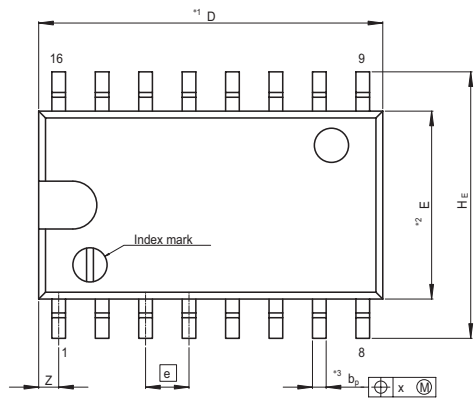


Package Dimensions

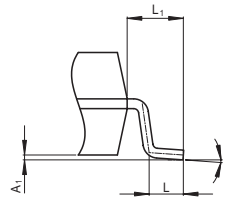


HD74HC85

JEITA Package Code P-SOP16-5.5x10.06-1.27	RENESAS Code PRSP0016DH-B	Previous Code FP-16DAV	MASS[Typ.] 0.24g
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Terminal cross section
(Ni/Pd/Au plating)



Detail F

NOTE)
1. DIMENSIONS*1 (Nom)*AND*2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION*3*DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	10.06	10.5
E	—	5.50	—
A ₂	—	—	—
A ₁	0.00	0.10	0.20
A	—	—	2.20
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	7.50	7.80	8.00
e	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L ₁	—	1.15	—

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Renesas Technology Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
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Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.

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Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

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Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China
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Renesas Technology Singapore Pte. Ltd.

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Tel: <82> 2-796-3115, Fax: <82> 2-796-2145

Renesas Technology Malaysia Sdn. Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510